

MEPTEC

**3<sup>rd</sup> Annual Technical Symposium  
on Thermal Management in  
Microelectronics  
2007**

**“The Heat is On:  
Thermal Management in Microelectronics”**

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## TABLE OF CONTENTS

### **KEYNOTE SPEECH**

<b>The Future of Thermal Engineering – Far from a Stand-Alone Discipline.....</b>	<b>1</b>
<i>Jerry Bartley</i>	

### **SESSION ONE: THERMAL MANAGEMENT OVERVIEW – TRENDS AND TECHNOLOGY**

<b>IC Power Dissipation Challenges.....</b>	<b>21</b>
<i>Maniam Alagaratnam</i>	
<b>Thermal Management of Mobile Electronics: A Case Study in Densification.....</b>	<b>33</b>
<i>Hongyu Ran PhD, Ilyas Mohammed, Laura Mirkarimi</i>	
<b>Thermal Challenges in ICs and Memory: Hot Spots - Passive Cooling and Beyond .....</b>	<b>63</b>
<i>Devesh Mathur PhD, Andy Delano PhD</i>	

### **SESSION TWO: ISSUES IN DESIGN AND ANALYSIS OF ADVANCED PACKAGES**

<b>New Techniques for Chip and Package Thermal Modeling .....</b>	<b>89</b>
<i>Sherman Ikemoto, Edmund Cheng PhD</i>	
<b>High Power Packaging: Materials, Design and Analysis Considerations .....</b>	<b>114</b>
<i>Jesse Galloway PhD.</i>	
<b>Thermal Behavior and Data Processing for Multi-Chip Packages: Lateral, Stacked, PoP and PiP .....</b>	<b>137</b>
<i>Roger Emigh PhD</i>	

### **SESSION THREE: THERMAL EFFECTS AND SOLUTIONS IN THE BACK END OPERATION**

<b>Semiconductor Thermal Resistance – Standards versus Real Life .....</b>	<b>153</b>
<i>Bernie Siegal</i>	
<b>Limitations of Traditional Burn-In and Test Methods Due to Thermal Implications.....</b>	<b>179</b>
<i>Chris Lopez, James Forster PhD</i>	
<b>Challenges of Process Variation and Temperature at Burn-In .....</b>	<b>199</b>
<i>Kelly Black, Ken Kelly</i>	

## **SESSION FOUR; THERMAL MANAGEMENT IN CHALLENGING PRODUCT APPLICATIONS**

<b>Mitigating Semiconductor Hot Spots.....</b>	213
<i>Seri Lee PhD</i>	
<b>XBOX360 Thermal System Design and Verification.....</b>	236
<i>Julia Purtell, Paul Wang, Jeff Reents, Michael Miller</i>	
<b>System Design Challenges.....</b>	259
<i>Andre Ali</i>	

## **Author Index**